



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Siamak Fazelpour

Application Serial No.: 10/025,438

Filed: December 19, 2001

Title: Method For Integrating Passives
On-Die Utilizing Under Bump Metal
And Related Structure

Group Art Unit: 2812

Examiner: Nguyen, Ha T.

Notice of Allowance: May 19, 2004

ISSUE FEE AND FEE FOR FIVE COPIES OF THE ISSUED PATENT

Mail Stop Issue Fee
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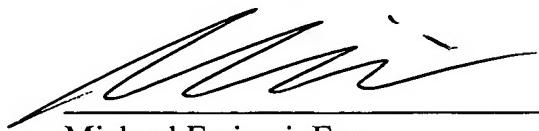
Dear Sir/Madam:

Enclosed, please find the completed "Issue Fee Transmittal" form and a "Payment by Credit Card" form (PTO-2038) in the amount of \$1,345.00 to cover the issue fee and fee for five (5) copies of the issued patent. The drawings filed on December 19, 2001 have been accepted as formal drawings by the Examiner.

An early issuance of the present application is respectfully requested.

Respectfully Submitted;
FARJAMI & FARJAMI LLP

Dated: 5/27/04



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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed: Mail Stop Issue Fee, Commissioner for Patents P.O. Box 1450, Alexandria, VA 22313-1450

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